



Integrated Device Technology, Inc.

CMOS SERIAL-TO-PARALLEL FIFO 2048 x 9 BIT & 4096 x 9 BIT

IDT 72132
IDT 72142

FEATURES:

- 35ns parallel port access time
- 50 MHz serial port shift rate
- Easily expandable in depth and width
- Programmable word lengths including 8, 9, 16-18, and 32-36 bits using Flexishift™ serial input without any additional components
- Multiple status flags: Full, Almost-Full (1/8 from full), Half-Full, Almost-Empty (1/8 from empty), and Empty
- Asynchronous and simultaneous read and write operations
- Dual-ported zero fall-through time architecture
- Retransmit capability in single device mode
- Produced with high-performance, low-power CEMOS™ technology
- Available in a 28-pin ceramic and plastic DIP, 32-pin LCC and J-leaded PLCC
- Military product compliant to MIL-STD-883, Class B

DESCRIPTION:

The IDT72132/72142 are high-speed, low-power serial-to-parallel FIFOs. These FIFOs are ideally suited to serial communications applications, tape/disk controllers, and local area networks (LANs). The IDT72132/72142 can be configured with the IDT's parallel-to-serial FIFOs (IDT72131/72141) for bidirectional serial data buffering.

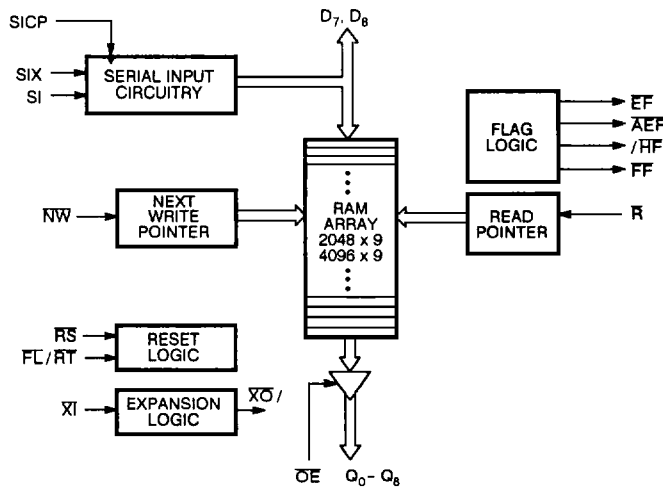
The FIFO has a serial input port and a 9-bit parallel output port. Wider and deeper serial-to-parallel data buffers can be built using multiple IDT72132/72142 chips. IDT's unique Flexishift™ serial expansion logic (SIX, NW) makes width expansion possible with no additional components. These FIFOs will expand to a variety of word widths including 8, 9, 16, and 32 bits. The IDT72132/142 can also be directly connected for depth expansion.

Five flags are provided to monitor the FIFO. The full and empty flags prevent any FIFO data overflow or underflow conditions. The Almost-Full (7/8), Half-Full, and Almost-Empty (1/8) flags signal memory utilization within the FIFO.

The IDT72132/72142 is fabricated using IDT's high-speed submicron CEMOS™ technology. Military grade product is manufactured in compliance with the latest revision of MIL-STD-883, Class B.

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FUNCTIONAL BLOCK DIAGRAM

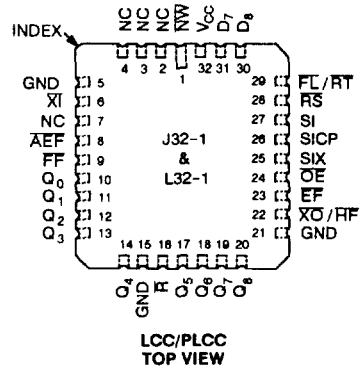
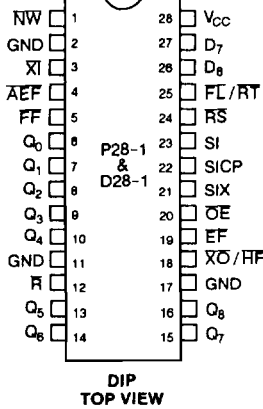


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MILITARY AND COMMERCIAL TEMPERATURE RANGES

JANUARY 1989

PIN CONFIGURATIONS



PIN DESCRIPTIONS

SYMBOL	NAME	I/O	DESCRIPTION
SI	Serial Input	I	Serial data is shifted in least significant bit first. In the serial cascade mode, the Serial Input (SI) pins are tied together and SIX plus D7, D8 determine which device stores the data.
RS	Reset	I	When RS is set low, internal READ and WRITE pointers are set to the first location of the RAM array. HF and FF go high, and AEF and EF go low. A reset is required before an initial WRITE after power-up. R must be high during a RS cycle.
NW	Next Write	I	To program the Serial In word width, connect NW with one of the Data Set pins (D7, D8)
SICP	Serial Input Clock	I	Serial data is read into the serial input register on the rising edge of SICP. In both Depth and Serial Word Width Expansion modes, all of the SICP pins are tied together.
R	Read	I	When READ is low, data can be read from the RAM array sequentially, independent of SICP. In order for READ to be active, EF must be high. When the FIFO is empty (EF-low), the internal READ operation is blocked and Q0 - Q8 are in a high impedance condition.
FL/RT	First Load/Retransmit	I	This is a dual purpose input. In the single device configuration (XI grounded), activating retransmit (FL/RT-low) will set the internal READ pointer to the first location. There is no effect on the WRITE pointer. SOCP and W must be high before setting FL/RT low. Retransmit is not possible in depth expansion. In the depth expansion configuration, FL/RT grounded indicates the first activated device.
XI	Expansion In	I	In the single device configuration, XI is grounded. In depth expansion or daisy chain expansion, XI is connected to XO (expansion out) of the previous device.
SIX	Serial Input Expansion	I	In the Expansion mode, SIX pin is tied high on the device that will source the lower order bits of the serial word. The device or devices that source the next higher order serial bits have their SIX pin (or pins) tied to the D8 pin of the device that will source the next lower order bits of the serial word. For single device operation, SIX is tied high.
OE	Output Enable	I	When OE is set low, the parallel output buffers receive data from the RAM array. When OE is set high, parallel three state buffers inhibit data flow.
Q0 - Q8	Data Output	O	Data outputs for 9-bit wide data
FF	Full Flag	O	When FF goes low, the device is full and data must not be clocked in by SOCP. When FF is high, the device is not full.
EF	Empty Flag	O	When EF goes low, the device is empty and further READ operations are inhibited. When EF is high, the device is not empty.
AEF	Almost-Empty/Almost-Full Flag	O	When AEF is low, the device is empty to 1/8 full or 7/8 to completely full. When AEF is high, the device is greater than 1/8 full, but less than 7/8 full.
XO/RF	Almost-Empty/Almost-Full Flag	O	This is a dual purpose output. In the single device configuration (XI grounded), the device is more than half full when HF is low. In the depth expansion configuration (XO connected to XI of the next device), a pulse is sent from XO to XI when the last location in the RAM array is filled.
D7, D8	Data Set	O	The appropriate Data Set pin (D7, D8) is connected to NW to program the Serial In data word width. For example: Q7 - NW programs a 8-bit word width, Q8 - NW programs a 9-bit word width, etc.
Vcc	Power Supply		Single power supply of 5V.
GND	Ground		Single ground of 0V.

STATUS FLAGS

NUMBER OF WORDS IN FIFO		FF	AEF	HF	EF
IDT72132	IDT72142				
0	0	H	L	H	L
1-255	1-511	H	L	H	H
256-1024	512-2048	H	H	H	H
1025-1792	2049-3584	H	H	L	H
1793-2047	3585-4095	H	L	L	H
2048	4096	L	L	L	H

ABSOLUTE MAXIMUM RATINGS ⁽¹⁾

SYMBOL	RATING	COMMERCIAL	MILITARY	UNIT
V _{TERM}	Terminal Voltage with Respect to GND	-0.5 to +7.0	-0.5 to +7.0	V
T _A	Operating Temperature	0 to +70	-55 to +125	°C
T _{BIAS}	Temperature Under Bias	-55 to +125	-65 to +135	°C
T _{STG}	Storage Temperature	-55 to +125	-65 to +150	°C
I _{OUT}	DC Output Current	50	50	mA

NOTE:

1. Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

RECOMMENDED DC OPERATING CONDITIONS

SYMBOL	PARAMETER	MIN.	TYP.	MAX.	UNIT
V _{CCM}	Military Supply Voltage	4.5	5.0	5.5	V
V _{CC}	Commercial Supply Voltage	4.5	5.0	5.5	V
GND	Supply Voltage	0	0	0	V
V _{IH}	Input High Voltage Commercial	2.0	-	-	V
V _{IH}	Input High Voltage Military	2.2	-	-	V
V _{IL} ⁽¹⁾	Input Low Voltage Commercial & Military	-	-	0.8	V

NOTE:

1. 1.5V undershoots are allowed for 10ns once per cycle.

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DC ELECTRICAL CHARACTERISTICS

(Commercial: V_{CC} = 5V ±10%, T_A = 0°C to +70°C; Military: V_{CC} = 5V ±10%, T_A = -55°C to +125°C)

SYMBOL	PARAMETER	IDT72132/IDT72142 COMMERCIAL			IDT72132/IDT72142 MILITARY			UNIT
		MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	
I _{IL} ⁽¹⁾	Input Leakage Current (Any Input)	-1	-	1	-10	-	10	µA
I _{OL} ⁽²⁾	Output Leakage Current	-10	-	10	-10	-	10	µA
V _{OH}	Output Logic "1" Voltage	2.4	-	-	2.4	-	-	V
V _{OL}	Output Logic "0" Voltage	-	-	0.4	-	-	0.4	V
I _{CC1} ⁽³⁾	Power Supply Current	-	90	140	-	100	160	mA
I _{CC2} ⁽³⁾	Average Standby Current (R = W = RST = FL/RT = V _{IH})	-	8	12	-	12	25	mA
I _{CC3(L)} ^(3,4)	Power Down Current	-	-	2	-	-	4	mA
I _{CC3(S)} ^(3,4)	Power Down Current	-	-	8	-	-	12	mA

NOTES:

- Measurements with 0.4 ≤ V_{IN} ≤ V_{OUT}.
- R ≥ V_{IH}, 0.4 ≤ V_{OUT} ≤ V_{CC}
- I_{CC} measurements are made with outputs open.
- R_S = FL/RT = R̄ = V_{CC} - 0.2V; all other inputs ≥ V_{CC} - 0.2V or ≤ 0.2V

AC ELECTRICAL CHARACTERISTICS⁽¹⁾

(Commercial: $V_{CC} = 5V \pm 10\%$, $T_A = 0^\circ C$ to $+70^\circ C$; Military: $V_{CC} = 5V \pm 10\%$, $T_A = -55^\circ C$ to $+125^\circ C$)

SYMBOL	PARAMETER	COM'L.	MIL.	MILITARY AND COMMERCIAL				UNIT
		72132x35 72142x35 MIN. MAX.	72132x40 72142x40 MIN. MAX.	72132x50 72142x50 MIN. MAX.	72132x65 72142x65 MIN. MAX.	72132x80 72142x80 MIN. MAX.	72132x120 72142x120 MIN. MAX.	
t_s	Parallel Shift Frequency	- 22.2	- 20	- 15	- 12.5	- 10	- 7	MHz
t_{SICP}	Serial-In Shift Frequency	- 50	- 50	- 40	- 33	- 28	- 25	MHz
t_A	Access Time	- 35	- 40	- 50	- 65	- 80	- 120	ns
t_{RR}	Read Recovery Time	10	- 10	- 15	- 15	- 20	- 20	ns
t_{RPW}	Read Pulse Width	35	- 40	- 50	- 65	- 80	- 120	ns
t_{RC}	Read Cycle Time	45	- 50	- 65	- 80	- 100	- 140	ns
t_{RLZ}	Read Pulse Low to Data Bus at Low Z ⁽¹⁾	5	- 5	- 10	- 10	- 10	- 10	ns
t_{RHZ}	Read Pulse High to Data Bus at High Z ⁽¹⁾	- 20	- 25	- 30	- 30	- 35	- 35	ns
t_{DV}	Data Valid from Read Pulse High	5	- 5	- 5	- 5	- 5	- 5	ns
t_{OEZH}	Output Enable to High-Z (Disable) ⁽¹⁾	- 15	- 15	- 15	- 20	- 25	- 30	ns
t_{OELZ}	Output Enable to Low-Z (Enable) ⁽¹⁾	5	- 5	- 5	- 5	- 5	- 5	ns
t_{AOE}	Output Enable to Data Valid (Q_{0-g})	- 20	- 20	- 22	- 25	- 30	- 35	ns
t_{SIS}	Serial Data in Set-up Time to SICP Rising Edge	12	- 12	- 15	- 15	- 20	- 20	ns
t_{SIH}	Serial Data in Hold Time to SICP Rising Edge	0	- 0	- 0	- 0	- 5	- 5	ns
t_{SIX}	SIX Set-Up Time to SICP Rising Edge	5	- 5	- 5	- 5	- 5	- 5	ns
t_{SICW}	Serial in Clock Width High/Low	8	- 8	- 10	- 10	- 15	- 15	ns
t_{SICEF}	SICP Rising Edge (Bit 0 - First Word) to EF High	- 45	- 50	- 65	- 80	- 80	- 80	ns
t_{SICFF}	SICP Rising Edge (Bit 0 - First Word) to FF Low	- 30	- 35	- 40	- 50	- 60	- 60	ns
t_{SICF}	SICP Rising Edge to HF, AEF	- 45	- 50	- 65	- 80	- 80	- 80	ns
t_{RFFSI}	Recovery Time SICP After FF Goes High	15	- 15	- 15	- 15	- 20	- 20	ns
t_{REF}	Read Low to EF Low	- 30	- 35	- 45	- 60	- 60	- 60	ns
t_{RFF}	Read High to FF High	- 30	- 35	- 45	- 60	- 60	- 60	ns
t_{RF}	Read High to Transitioning HF and AEF	- 45	- 50	- 65	- 80	- 100	- 140	ns
t_{RPE}	Read Pulse Width After EF High	35	- 40	- 50	- 65	- 80	- 120	ns
t_{RSC}	Reset Cycle Time	45	- 50	- 65	- 80	- 100	- 140	ns
t_{RS}	Reset Pulse Width	35	- 40	- 50	- 65	- 80	- 120	ns
t_{RSS}	Reset Set-up Time	35	- 40	- 50	- 65	- 80	- 120	ns
t_{RSA}	Reset Recovery Time	10	- 10	- 15	- 15	- 20	- 20	ns
t_{RSF1}	Reset to EF and AEF Low	- 45	- 50	- 65	- 80	- 100	- 140	ns
t_{RSF2}	Reset to HF and FF High	- 45	- 50	- 65	- 80	- 100	- 140	ns
t_{RTC}	Retransmit Cycle Time	45	- 50	- 65	- 80	- 100	- 140	ns
t_{RT}	Retransmit Pulse Width	35	- 40	- 50	- 65	- 80	- 120	ns
t_{RTS}	Retransmit Set-up Time	35	- 40	- 50	- 65	- 80	- 120	ns
t_{RTR}	Retransmit Recovery Time	10	- 10	- 15	- 15	- 20	- 20	ns
t_{XOL}	Read/Write to X \bar{O} Low	- 35	- 40	- 50	- 65	- 80	- 120	ns
t_{XOH}	Read/Write to X \bar{O} High	- 35	- 40	- 50	- 65	- 80	- 120	ns
t_{XI}	XI Pulse Width	35	- 40	- 50	- 65	- 80	- 120	ns
t_{XIR}	XI Recovery Time	10	- 10	- 10	- 10	- 10	- 10	ns
t_{XIS}	XI Set-up Time	16	- 15	- 15	- 15	- 15	- 15	ns

NOTE:

1. Guaranteed by design minimum times, not tested.

AC TEST CONDITIONS

Input Pulse Levels	GND to 3.0V
Input Rise/Fall Times	3ns
Input Timing Reference Levels	1.5V
Output Reference Levels	1.5V
Output Load	See Figure 1

CAPACITANCE ($T_A = +25^\circ\text{C}$, $f = 1.0\text{MHz}$)

SYMBOL	PARAMETER ⁽¹⁾	CONDITIONS	MAX.	UNIT
C_{IN}	Input Capacitance	$V_{IN} = 0V$	10	pF
C_{OUT}	Output Capacitance	$V_{OUT} = 0V$	12	pF

NOTE:

1. This parameter is sampled and not 100% tested.

FUNCTIONAL DESCRIPTION

Serial Data Input

The serial data is input on the SI pin. The data is clocked in on the rising edge of SICP providing the Full Flag (FF) is not asserted. If the Full Flag is asserted then the next data word is inhibited from moving into the RAM array. NOTE: SICP should not be clocked while the Full Flag is low. If it is, then the input data will be lost.

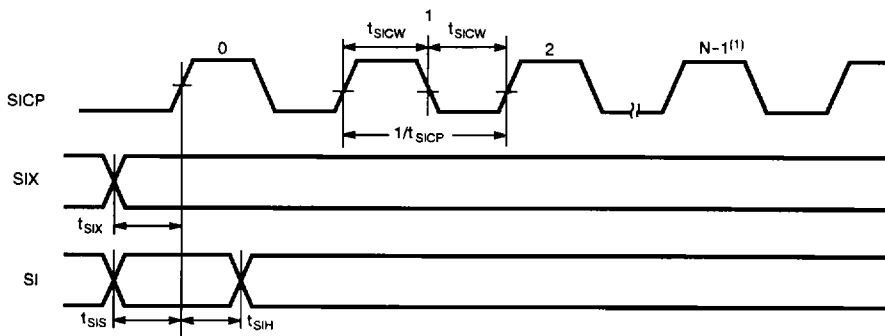


Figure 1. Write Operation

Parallel Data Output

A read cycle is initiated on the falling edge of Read (\bar{R}) provided the Empty Flag is not set. The output data is accessed on a first-in/first-out basis, independent of the ongoing write operations. The data is available t_A after the falling edge of \bar{R} and the output bus Q goes into high impedance after \bar{R} goes HIGH.

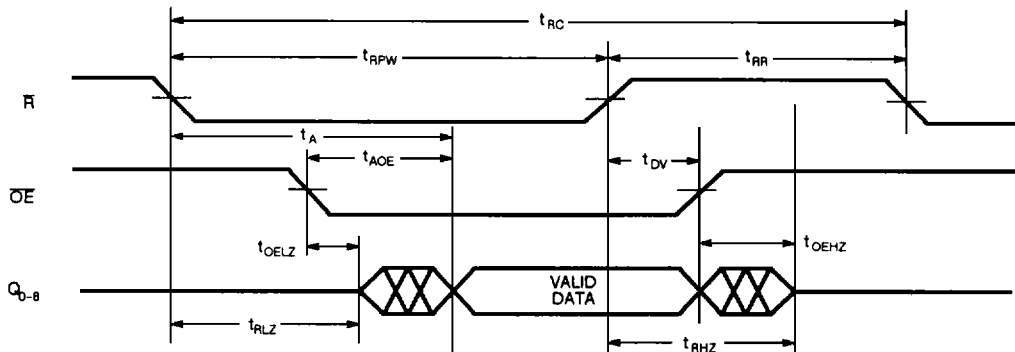


Figure 2. Read Operation

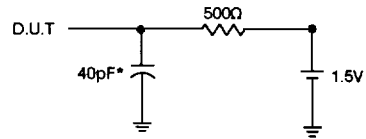


Figure A. Output Load.

*Includes jig and scope capacitances.

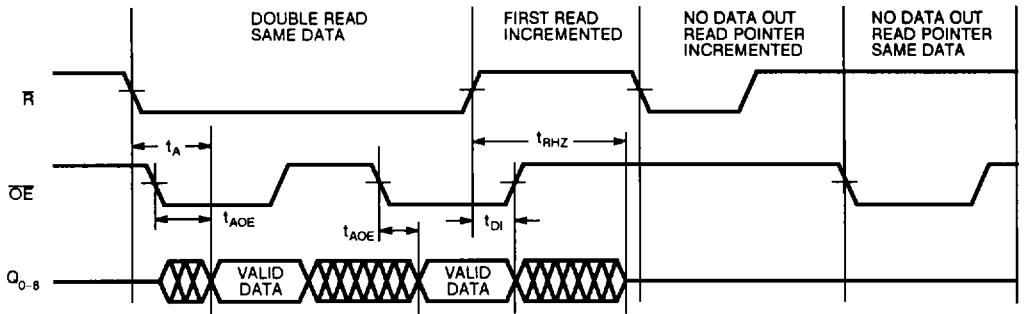
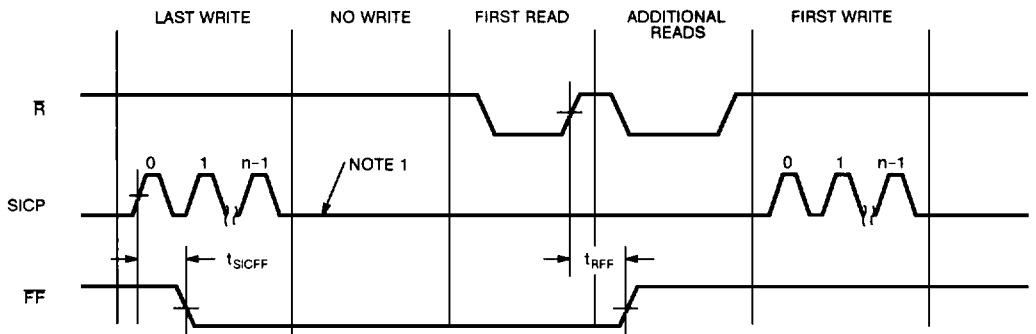


Figure 3. Read and Output Enable Timings



NOTE:

1. SICP should not be clocked until FF goes high.

Figure 4. Full Flag from Last Write to First Read

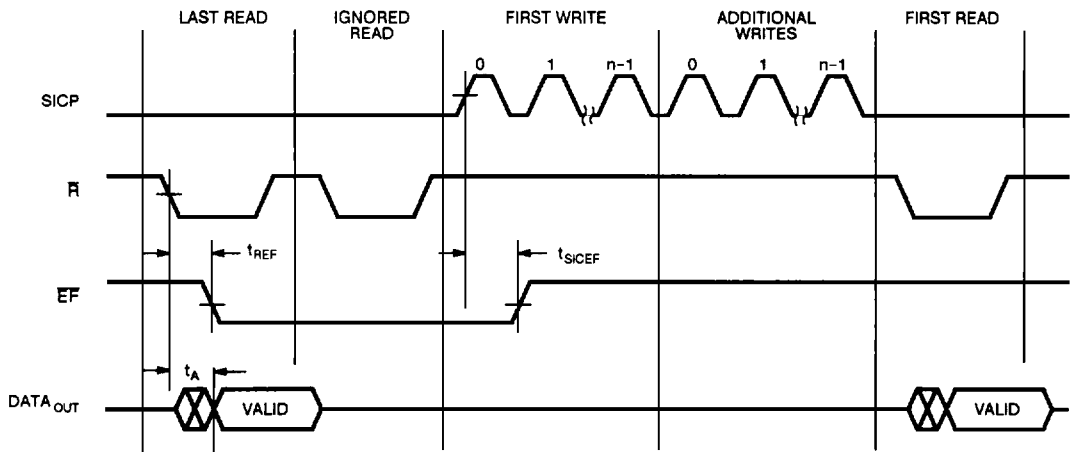


Figure 5. Empty Flag from Last Read to First Write

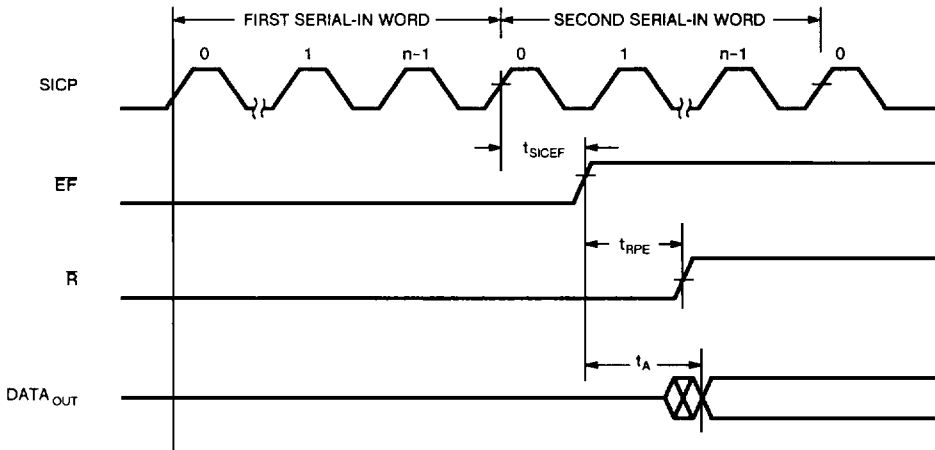
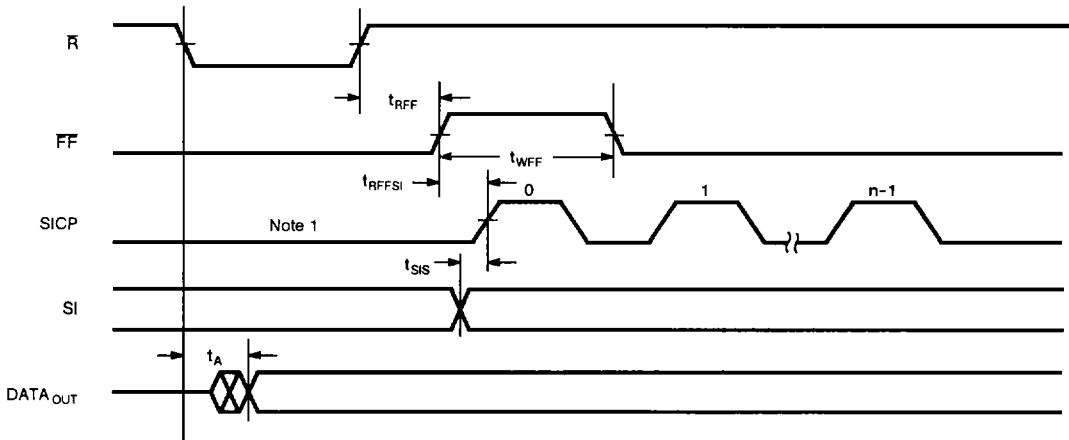


Figure 6. Empty Boundary Condition Timing

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NOTE:

1. SICIP must remain low until after FF goes high.

Figure 7. Full Boundary Condition Timing

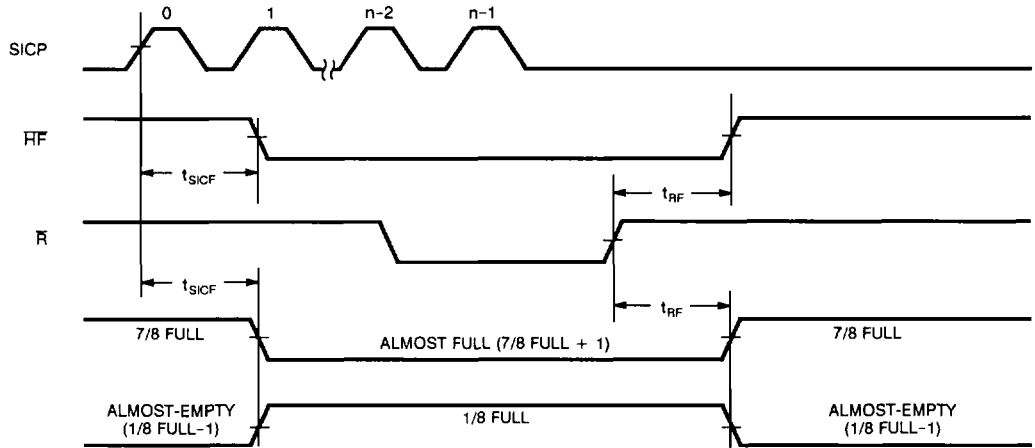
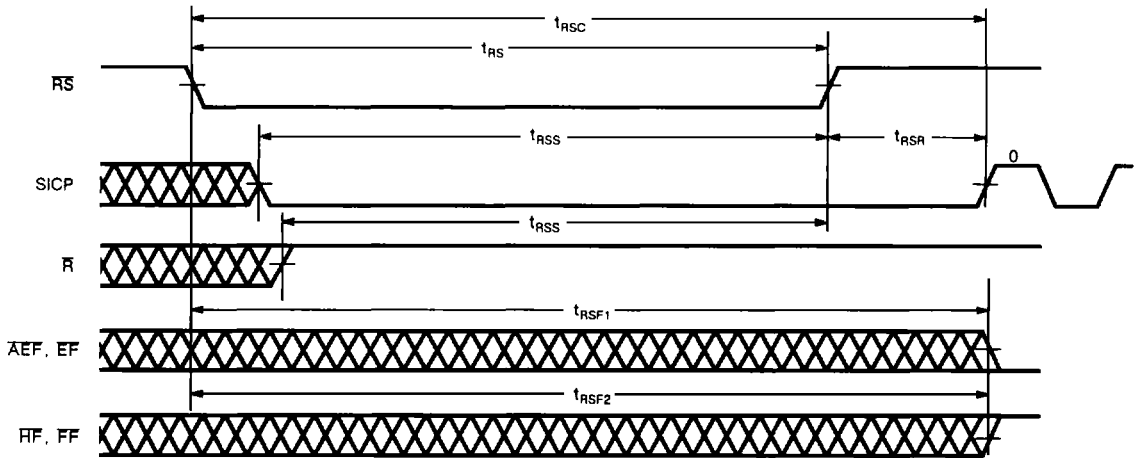


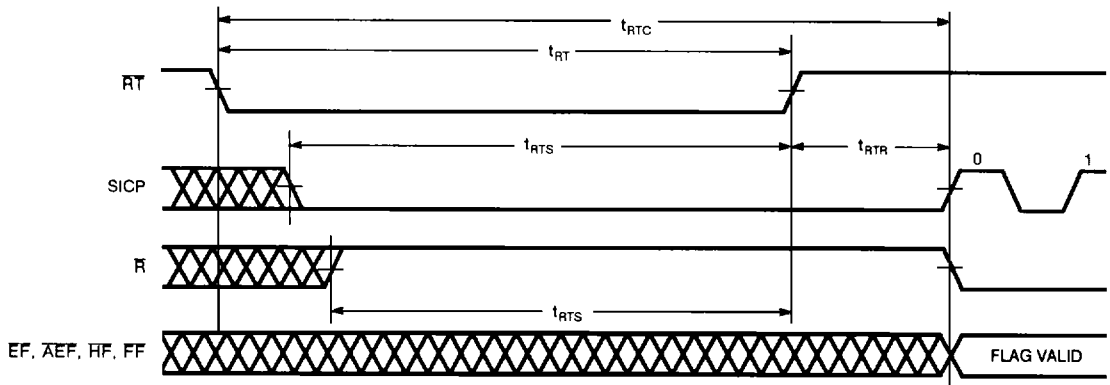
Figure 8. Half Full, Almost Full and Almost Empty Timings



NOTE:

1. EF, FF and HF may change status during Reset, but flags will be valid at t_{RSC} .

Figure 9. Reset



NOTE:

1. **EF, AEF, HF** and **FF** may change status during Retransmit, but flags will be valid at t_{RTC} .

Figure 10. Retransmit

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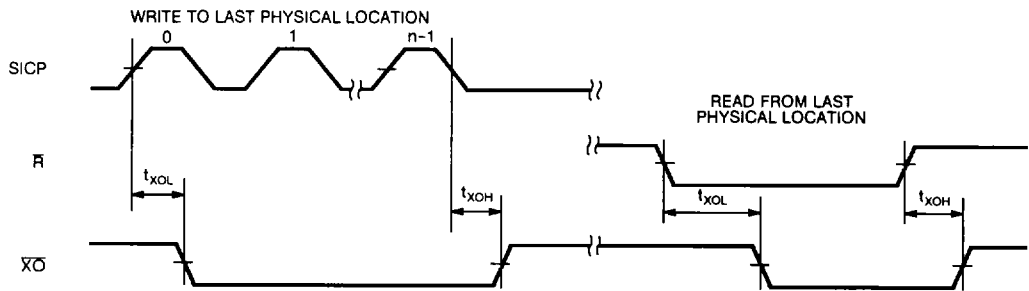


Figure 11. Expansion-Out

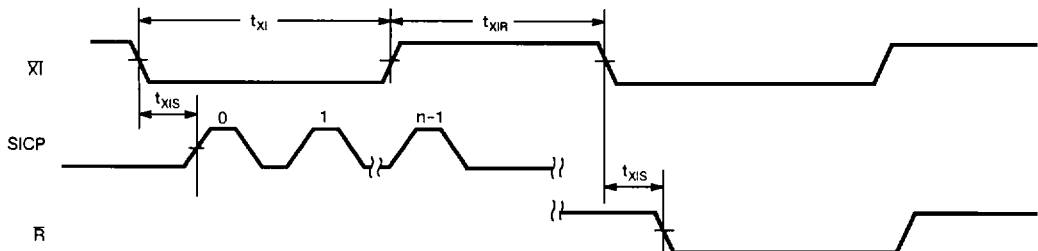


Figure 12. Expansion-In

OPERATING CONFIGURATIONS

Single Device Configuration

In the standalone case, the SIX line is tied HIGH and not used. On the first LOW-to-HIGH of the SICP clock, both of the Data Set

lines (D_7 , D_8) go low and a new serial word is started. The Data Set lines then go high on the equivalent SICP clock pulse. This continues until the D line connected to \overline{NW} goes high completing the serial word. The cycle is then repeated with the next LOW-to-HIGH transition of SICP.

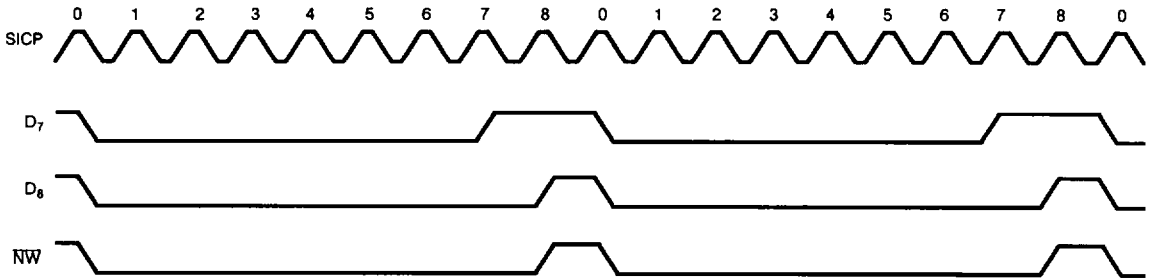
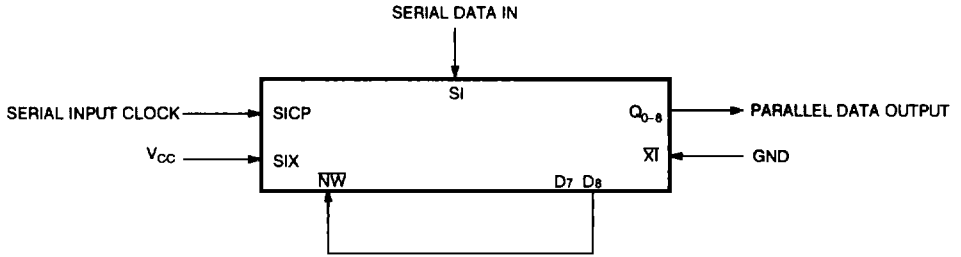


Figure 13. Nine-Bit Word Single Device Configuration

TRUTH TABLES

TABLE 1: RESET AND RETRANSMIT – SINGLE DEVICE CONFIGURATION/WIDTH EXPANSION MODE

MODE	INPUTS			INTERNAL STATUS		OUTPUTS		
	RS	FL	XI	READ POINTER	WRITE POINTER	AEF, EF	FF	HF
Reset	0	X	0	Location Zero	Location Zero	0	1	1
Retransmit	1	0	0	Location Zero	Unchanged	X	X	X
Read/Write	1	1	0	Increment ⁽¹⁾	Increment ⁽¹⁾	X	X	X

NOTE:

1. Pointer will Increment if appropriate flag is HIGH.

Width Expansion Configuration

In the cascaded case, word widths of more than 9 bits can be achieved by using more than one device. By tying the SIX line of the least significant device HIGH and the SIX of the subsequent devices to the appropriate Data Set lines of the previous devices, a cascaded serial word is achieved.

On the first LOW-to-HIGH clock edge of SICIP, both the Data Set lines go LOW. Just as in the standalone case, on each corresponding clock cycle, the equivalent Data Set line goes HIGH in order of least to most significant.

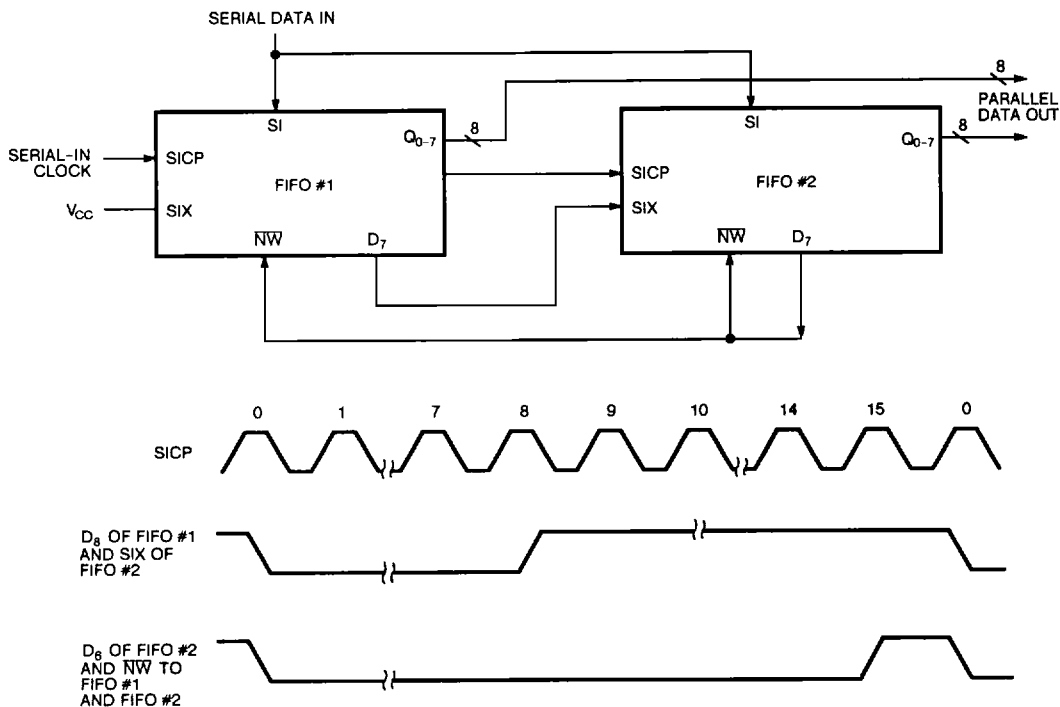


Figure 14. Serial-in to Parallel-Out Data of 16 Bits

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Depth Expansion (Daisy Chain) Mode

The IDT72132/42 can be easily adapted to applications where the requirements are for greater than 2048/4096 words. Figure 15 demonstrates Depth Expansion using three IDT72132/42. Any depth can be attained by adding additional IDT72132/42. The IDT72132/42 operates in the Depth Expansion configuration when the following conditions are met:

1. The first device must be designated by grounding the First Load (FL) control input.

2. All other devices must have in the high state.
3. The Expansion Out (XO) pin and Expansion In (XI) pin of each device must be tied together.
4. External logic is needed to generate a composite Full Flag (FF) and Empty Flag (EF). This requires the OR-ing of all s and OR-ing of all FFs (i.e., all must be set to generate the correct composite (FF) or (EF).
5. The Retransmit (RT) function and Half-Full Flag (HF) are not available in the Depth Expansion mode.

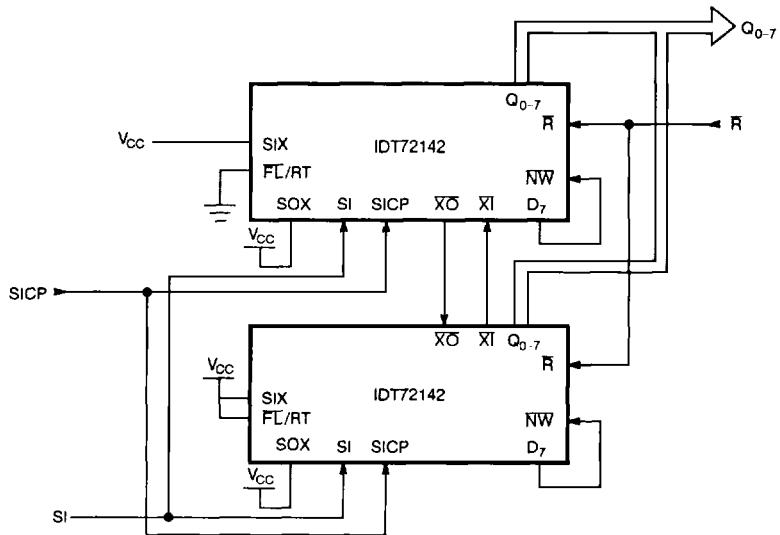


Figure 15. An 8K x 8 Serial-In Parallel-Out FIFO

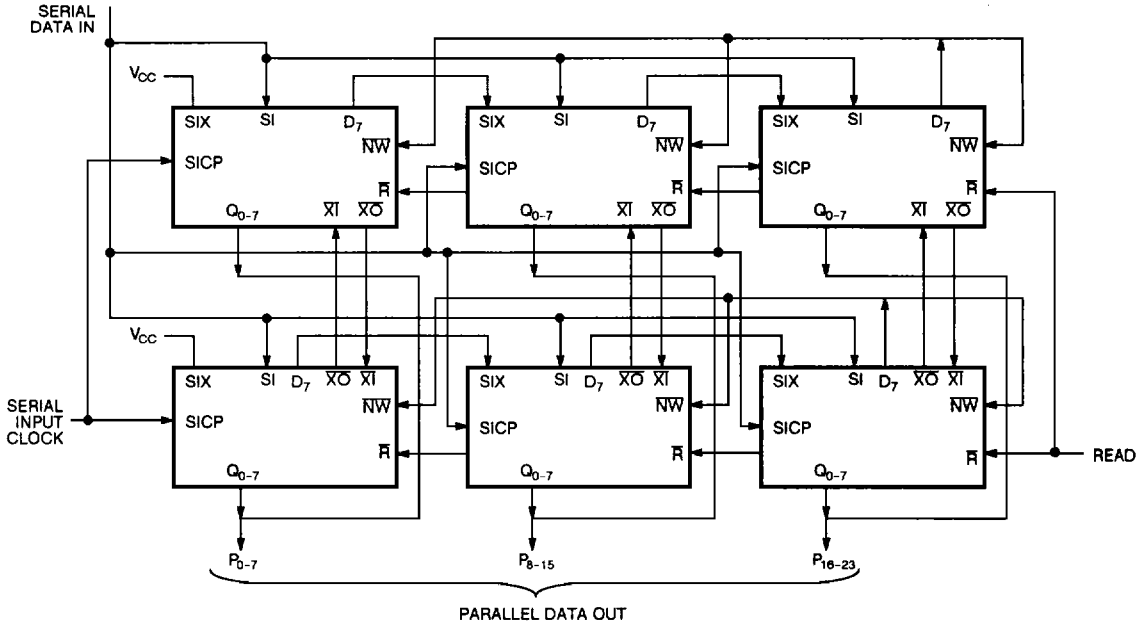
**TABLE 2: RESET AND FIRST LOAD TRUTH TABLE –
DEPTH EXPANSION/COMPOUND EXPANSION MODE**

MODE	INPUTS			INTERNAL STATUS		OUTPUTS	
	RS	FL	XI	READ POINTER	WRITE POINTER	EF	FF
Reset-First Device	0	0	(1)	Location Zero	Location Zero	0	1
Reset all Other Devices	0	1	(1)	Location Zero	Location Zero	0	1
Read/Write	1	X	(1)	X	X	X	X

NOTE:

1. RS = Reset Input, FL/RT = First Load/Retransmit, EF = Empty Flag Output, FF = Full Flag Output, XI = Expansion Input

SERIAL INPUT WITH WIDTH AND DEPTH EXPANSION



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Figure 16. An 8K x 24 Serial-In, Parallel-Out FIFO Using Six IDT72142s

ORDERING INFORMATION

IDT	XXXXX Device Type	A Power	999 Speed	A Package	A Process/ Temperature Range	
					Blank	Commercial (0°C to +70°C)
					B	Military (-55°C to +125°C) Compliant to MIL-STD-883, Class B
					P	Plastic DIP
					D	CERDIP
					J	Plastic Leaded Chip Carrier
					L	Leadless Chip Carrier
					35	(50MHz serial shift rate)
					40	(50MHz serial shift rate)
					50	(40MHz serial shift rate)
					65	(33MHz serial shift rate)
					80	(28MHz serial shift rate)
					120	(25MHz serial shift rate)
					S	Standard Power
					L	Low Power
					72132	2048 x 9-Bit Parallel-Serial FIFO
					72142	4096 x 9-Bit Parallel-Serial FIFO

} Parallel Access Time (t_A)